



DESCRIPTION

The B2S~B10S is available in TO-269AA(MBS) package

FEATURES

- Plastic package has Underwrites Laboratory Flammability Classification 94V-0
- Glass passivated chip junctions
- High surge overload rating: 35A peak
- Saves space on printed circuit boards
- High temperatures soldering guaranteed: 260°C/10 seconds.
- RoHS Compliant
- Available in TO-269AA package

ORDERING INFORMATION

Package Type	Part Number
TO-269AA (MBS)	B2S
	B4S
	B6S
	B8S
	B10S
Note	3,000pcs/Reel
AiT provides all RoHS Compliant Products	

MECHANICAL DATA

Case: molded plastic body over passivated junctions

Terminals: Plated leads solderable per

MIN-STD-750, Method 2026

Mounting position: Any

Weight: 0.078 oz., 0.22g



ABSOLUTE MAXIMUM RATINGS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase. half wave. 60HZ. resistive or inductive load. For capacitive load. derate current by 20 %

Parameter	Symbol	B2S	B4S	B6S	B8S	B10S	Unit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	200	400	600	800	1000	V
Maximum Recurrent Peak Reverse Voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	200	400	600	800	1000	V
Maximum Average Forward Output Rectified Current on glass-epoxy P.C.B on aluminum substrate	$I_{(AV)}$	0.5 ^{NOTE1} 0.8 ^{NOTE2}					A
Peak Forward Surge Current 8.3ms Single half-sine-wave superimposed on rated load.	I_{FSM}	35.0					A
Maximum Forward Voltage drop per leg at 0.4A	V_F	0.50			0.70		V
Maximum DC Reverse Current at $T_A = 25^\circ\text{C}$ at Rated DC Blocking Voltage per $T_A = 125^\circ\text{C}$	I_R	0.5 10.0					mA
Typical Junction Capacitance per leg at 4.0V	C_J	13					pF
Typical Thermal Resistance per leg	R_{QJA} R_{QJL} R_{QJA}	85 ^{NOTE1} 70 ^{NOTE2} 20 ^{NOTE1}					$^\circ\text{C/W}$
Operating Junction Temperature Range	T_J	-55 to 125					$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to 150					$^\circ\text{C}$

NOTE1: On glass epoxy P.C.B mounted on 0.05*0.05"(1.3*1.3mm) pads

NOTE2: On aluminum substrate P.C.B. with an area of 0.8*0.8"(20*20mm) mounted on 0.05*0.05"(1.3*1.3mm) solder pad



TYPICAL CHARACTERISTICS

Figure 1. Typical Forward Characteristic

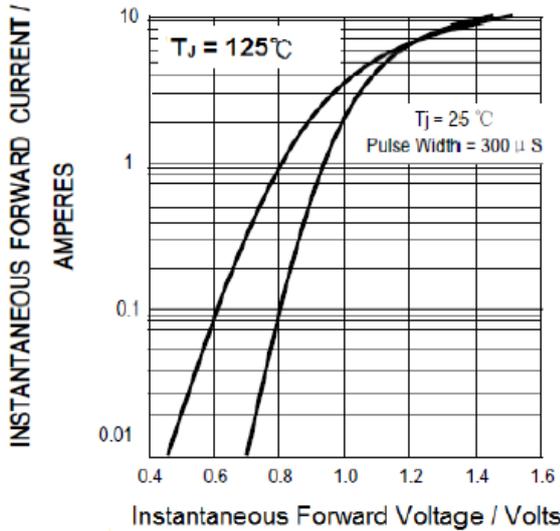


Figure 2. Typical Reverse Leakage Characteristics

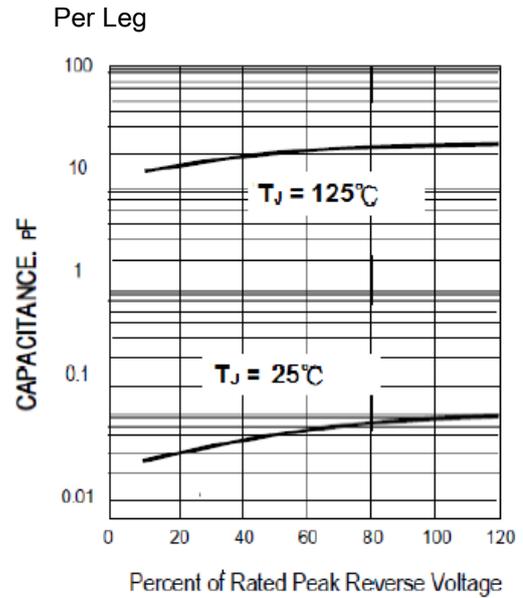


Figure 3. Derating Curve for Output Rectified Current

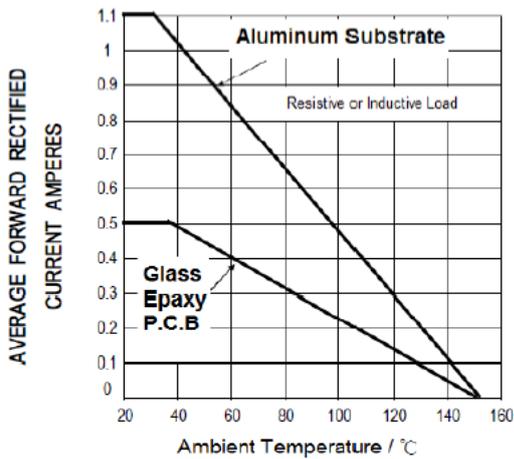
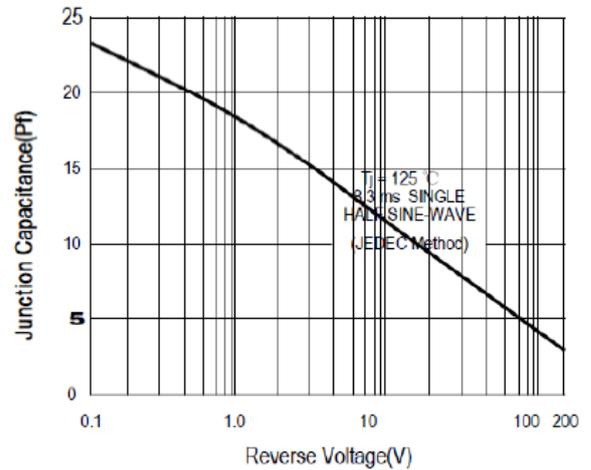


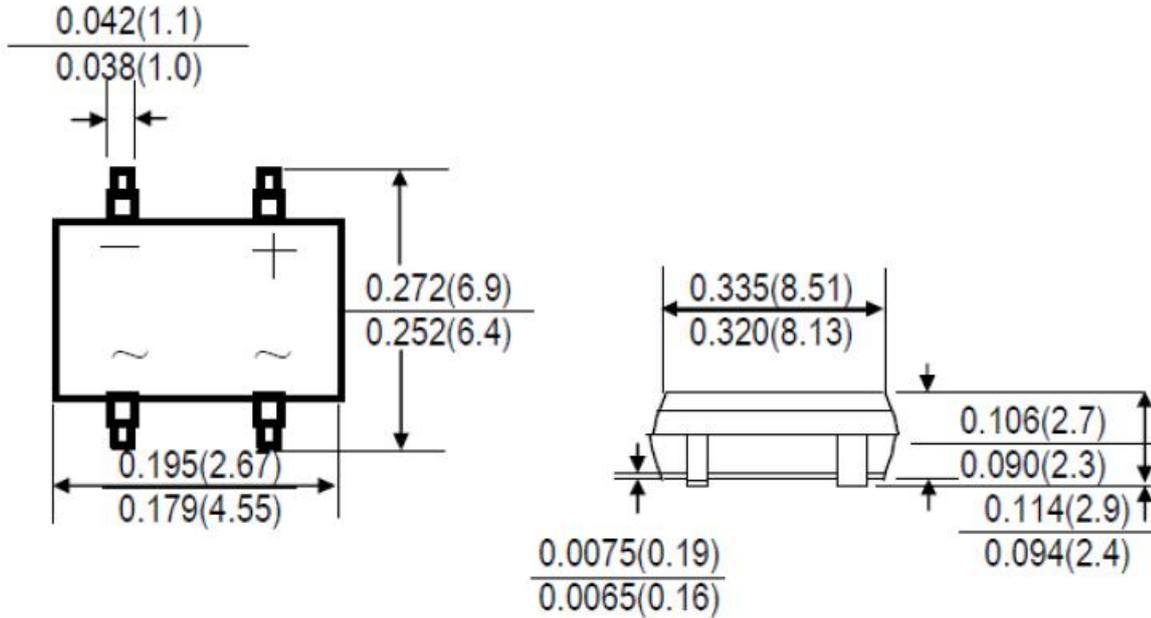
Figure 4. Typical Junction Capacitance Per Leg



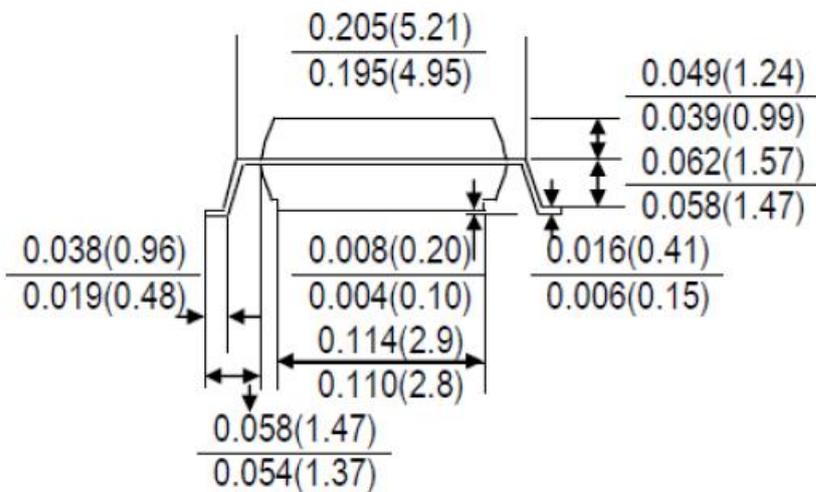


PACKAGE INFORMATION

Dimension in TO-269AA(MBS) (Unit: mm)



Dimensions in inches and (millimeters)





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